

# HIGH FREQUENCY PLANAR INDUCTORS

Ruggedized



- ⊙ Height: 7.4mm MAX
- ⊙ Footprint: 19.8mm x 19.6mm MAX
- ⊙ Current Rating: up to 73A
- ⊙ Inductance Range: 0.405 $\mu$ H to 6.2 $\mu$ H
- ⊙ Operating Temperature: -40°C to +130°C
- ⊙ Moisture Sensitivity Level: 1

## Electrical Specifications @ 25°C

Part Number	Inductance @ Irated ( $\mu$ H $\pm$ 15%)	Irated <sup>3</sup> (ADC)	DCR (m $\Omega$ )		Inductance @ 0 ADC ( $\mu$ H $\pm$ 15%)	Saturation Current <sup>4</sup>		Heating Current <sup>5</sup> (A)
			TYP	MAX		25°C	100°C	
<b>2-TURN (LOW-LOSS) SERIES</b>								
PL10100	0.45	73	0.38	0.48	0.45	95	80	73
PL10101	0.63	54	0.38	0.48	0.65	63	53	73
PL10102	0.85	39	0.38	0.48	0.91	46	37	73
PL10103	1.05	30	0.38	0.48	1.10	35	30	73
PL10104	1.25	25	0.38	0.48	1.30	29	26	73
PL10105	1.45	21	0.38	0.48	1.50	24	22	73
<b>2-TURN SERIES</b>								
PL10106	0.45	52	0.78	0.98	0.45	95	80	52
PL10107	0.63	52	0.78	0.98	0.65	63	53	52
PL10108	0.85	39	0.78	0.98	0.91	46	37	52
PL10109	1.05	30	0.78	0.98	1.10	35	30	52
PL10110	1.25	25	0.78	0.98	1.30	29	26	52
PL10111	1.45	21	0.78	0.98	1.50	24	22	52
<b>3-TURN SERIES</b>								
PL10112	0.95	42	1.15	1.43	1.00	68	54	42
PL10113	1.40	36	1.15	1.43	1.50	43	35	42
PL10114	1.90	25	1.15	1.43	2.00	29	25	42
PL10115	2.40	20	1.15	1.43	2.50	23	21	42
PL10116	2.80	15	1.15	1.43	3.00	18	16	42
PL10117	3.40	12	1.15	1.43	3.50	15	13	42
<b>4-TURN SERIES</b>								
PL10118	1.60	37	1.44	1.80	1.60	55	43	37
PL10119	2.40	30	1.44	1.80	2.42	35	27	37
PL10120	3.30	17	1.44	1.80	3.60	20	18	37
PL10121	4.00	14	1.44	1.80	4.40	16	15	37
PL10122	4.90	11	1.44	1.80	5.34	13	12	37
PL10123	5.80	9	1.44	1.80	6.20	11	10	37

### NOTES:

1. Add suffix "NL" for RoHS (Non-Lead) compliant version; i.e. PL10101 becomes **PL10101NL**.
2. For Tape & Reel packaging, add "T" suffix at the end of the part number: i.e. **PL10101T**
3. The rated current as listed is either 85% of the saturation current or the heating current, depending on which value is lower.
4. The saturation current is the current which causes the inductance to drop by 15% at the stated ambient temperature (25°C and 100°C). This current is determined by placing the component in the specified ambient environment and applying a short duration pulse current (to eliminate self-heating effects) to the component.
5. The heating current is the DC current which causes the temperature of the part to increase by approximately 45°C. This current is determined by mounting the component on a PCB with 0.25" wide, 2 oz. equivalent copper traces, and applying the current to the device for 30 minutes with no forced air cooling.
6. In high volt\*time applications, additional heating in the component can occur due to core losses in the inductor which may necessitate derating the current in order to limit the temperature rise of the component. In order to determine the approximate total losses (or temperature rise) for a given application, the total copper and core losses should be taken into account. For approximate value of core losses, in a given application, use the core loss graph on page 24.
7. Meets solerability test per IPC/EIA J-STD-002B using flux type ORLO.

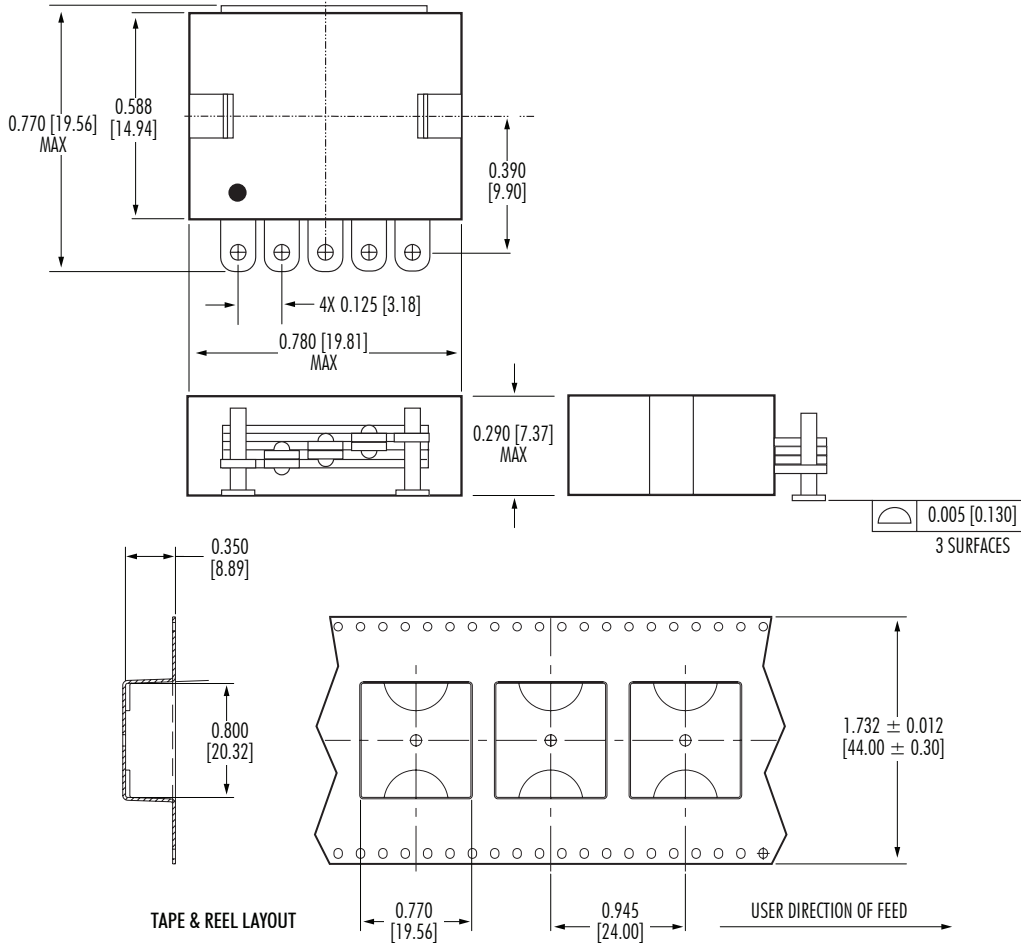


## Mechanicals

PL101XX

Dimensions: inch [mm]  
Tolerance (unless otherwise specified):  $\pm 0.010$  [0.25]

Weight: .....TBD  
Tray: .....TBD



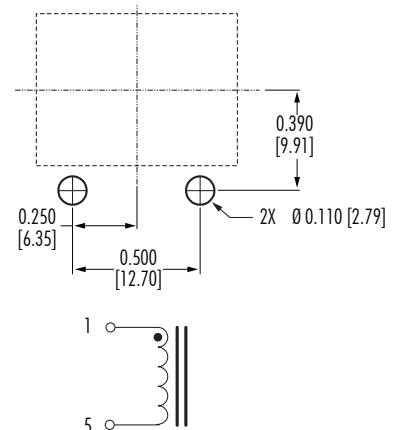
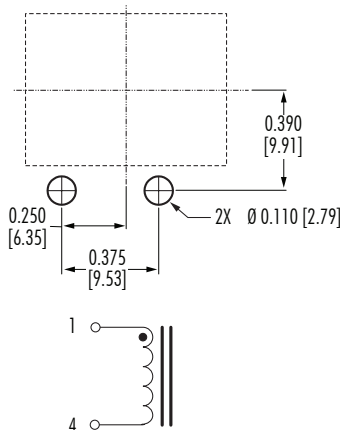
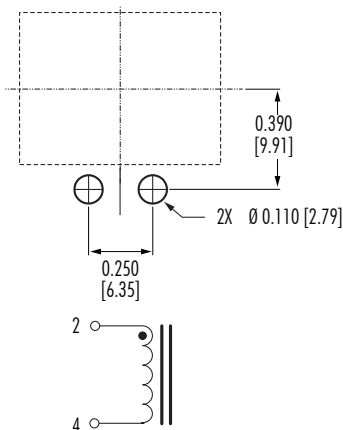
## Suggested Pad Layout and Schematics

PL101XX

PL10100 - PL10111  
0.405 to 1.50  $\mu$ H  
21 to 73 ADC

PL10112 - PL10117  
1.00 to 3.40  $\mu$ H  
12 to 42 ADC

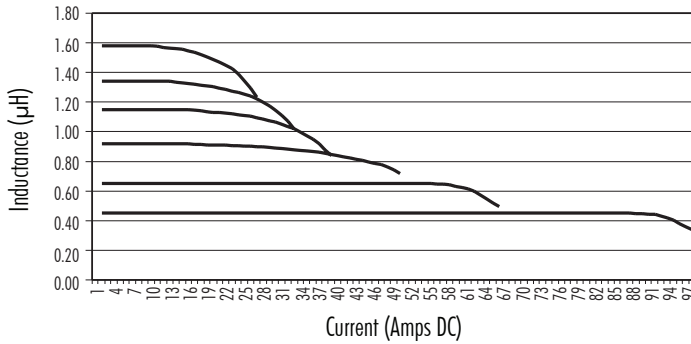
PL10118 - PL10123  
1.60 to 6.20  $\mu$ H  
9 to 37 ADC



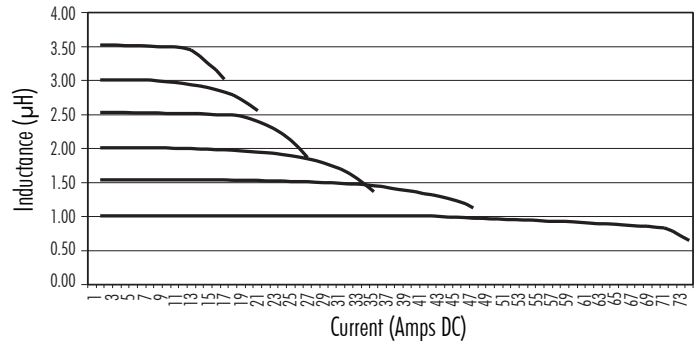
## Inductance vs. Current Characteristics (25°C)

### PL101XX

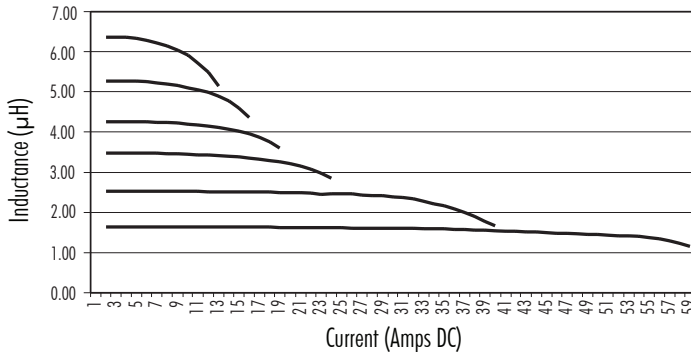
PL10110 - PL10111



PL10112 - PL10117



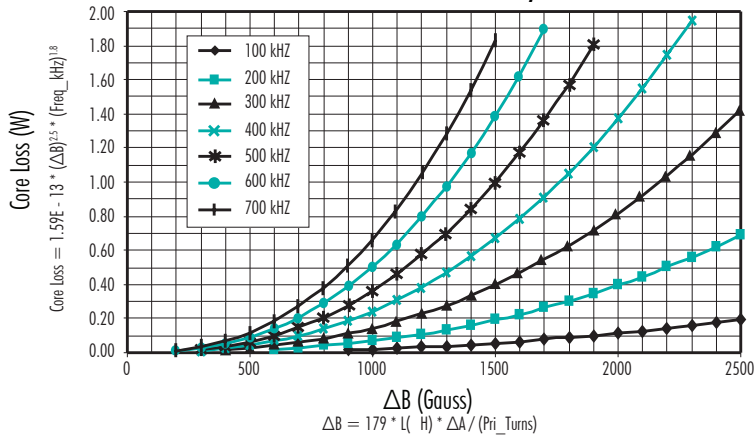
PL10118 - PL10123



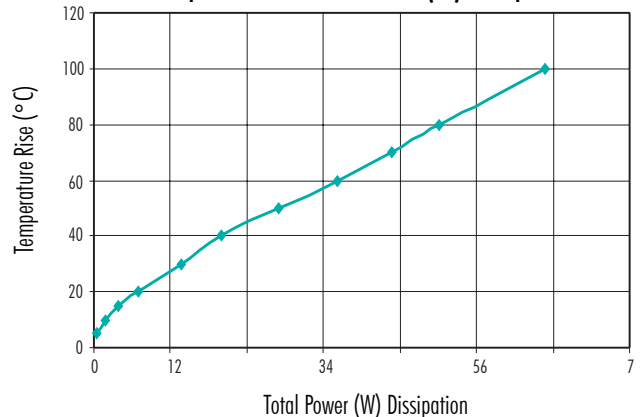
## Measurement Charts

### PL101XX

Core Loss vs. Flux Density



Temperature Rise vs. Power (W) Dissipation



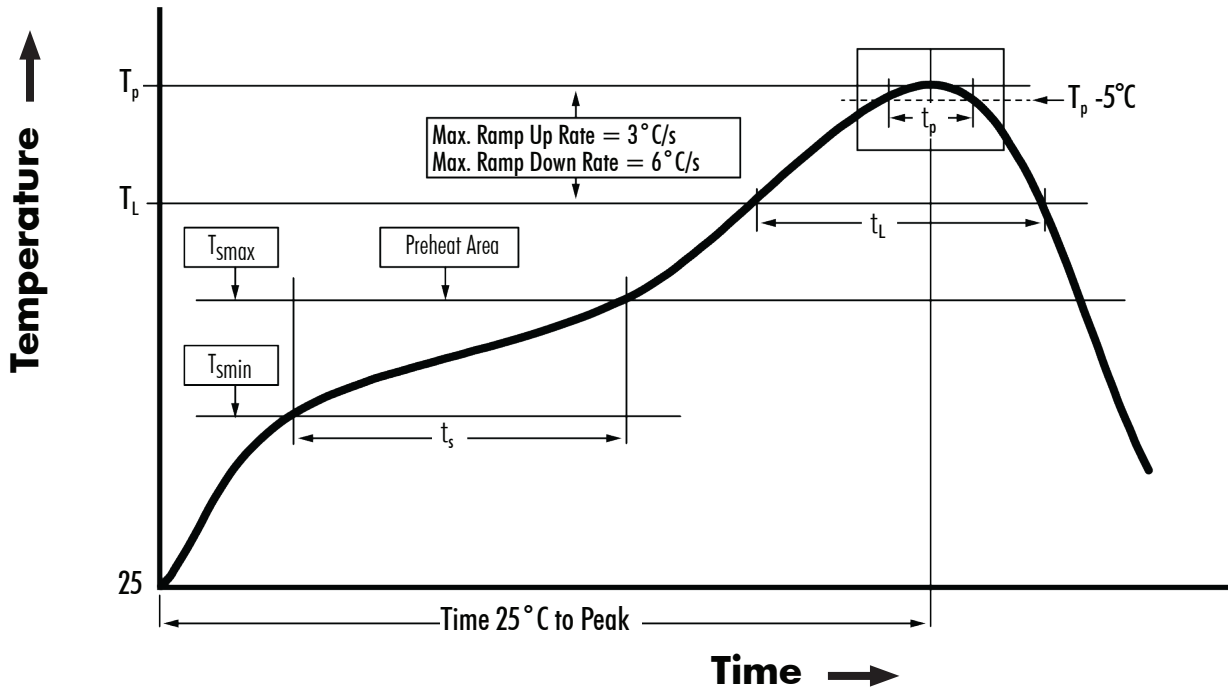
Total Power Dissipation = Copper Loss (W) + Core Loss (W)

Copper Loss (W) =  $\text{Current (rms)}^2 \cdot \text{DCR (m}\Omega) / 1000$

Core Loss (W) = per table



## Recommended Reflow Profile (Based on J-STD-020D)



$T_{SMIN}$ (°C)	$T_{SMAX}$ (°C)	$T_L$ (°C)	$T_p$ (°C MAX)	$t_s$ (s)	$t_L$ (s)	$t_p$ (s MAX)	Ramp-up rate ( $T_L$ to $T_p$ )	Ramp-down rate ( $T_p$ to $T_L$ )	Time 25°C to peak temperature (s MAX)
<b>Tin/Lead Profile</b>									
100	150	183	235	60 - 120	60 - 150	20	3°C/s MAX	6°C/s MAX	360
<b>Non-Lead Profile</b>									
150	200	217	245	60 - 120	60 - 150	30	3°C/s MAX	6°C/s MAX	480

### NOTES:

1. All temperatures measured on the package leads.
2. Maximum number of reflow cycles not to exceed 2.
3. Reflow cycle applies only to surface mount parts.

